IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Tatayabas et al.

Title:

Filed:

POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER

FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION

Docket No.:

884.946US1

June 30, 2003

Examiner:

Howard Weiss

Serial No.: 10/612,328

Due Date: October 14, 2005

Group Art Unit: 2814

## MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

. We are transmitting herewith the following attached items (as indicated with an "X"):

Return postcard.

Amendment and Response (6 pgs.).

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

Reg. No. 37,650

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this Sth day of September, 2005.

Name

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)

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## S/N 10/612,328 IN THE UNITED SPATES PATENT AND TRADEMARK OFFICE

Applicant: James C Matayabas et al. Examiner: Howard Weiss

Serial No.: 10/612,328 Group Art Unit: 2814

Filed: June 30, 2003 Docket No.: 884.946US1

Title: POLYMER SOLDER HYBRID INTERFACE
MATERIAL WITH IMPROVED SOLDER FILLER

PARTICLE SIZE AND MICROELECTRONIC

PACKAGE APPLICATION

Assignee: Intel Corporation Customer Number: 21186

## **AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

This responds to the Office Action mailed on <u>July 14, 2005</u>. Please amend the above-identified patent application as follows.

**PATENT**